

# **DYNAMIC CONNECTOR D1100D SERIES TIN PLATING**

#### 1. Introduction

#### 1.1 Purpose

This document provides the qualification summary of TE Connectivity Dynamic D-1000 Tin plated connectors produced in TE Suzhou plant (TECC).

#### 1.2 Scope

This specification covers the electrical, mechanical, and environmental performance of Dynamic D-1000H Tin plated connectors. Testing was performed from 2018/01/17 to 2018/01/31.

#### 1.3 Conclusion

Based on the test results, the parts in the table 1 meet the performance requirements of Product Specification, 108-78298 Rev E.

#### 1.4 Product Description

		Mating	Mating
<b>Testing part</b>	Testing part description	housing	contact
1-2271888-4	HDR ASSY (H-TYPE) 2.0mm Pitch 28POS. Tin plating	1-1827863-4	1871745-1

Table 1 test products



## 2. Qualification Test Sequence

		試験グループ Test Group								
試験項目	Test or Examination	1	2	3	4	5	6	7	8	9
	RETEROTOR TENDENTIAL TON				試	験順			-	
and the same and the same of t	54	J., .			Test S	Sequen	ce (a)			
製品の確認検査	Confirmation of Product	1,3	1,4	1,3	1,3	1,3	1,4	1,6	1,7	1,4
総合抵抗 (ローレベル)	Termination Resistance (Low Level)							2,5	2,6	2,5
耐電圧	Dielectric withstanding Voltage						3			
絶縁抵抗	Insulation Resistance	900	8	8		8 3	2		8	8
温度上昇	Temperature Rising					2	9	9	9	9
振動 (高周波)	Vibration (High Frequency)							3	3	6
衝撃	Physical Shock	i i	Ĩ					4		
コネクタ挿入力	Connector Mating								3	è
コネクタ引抜カ	Connector Unmating	900	8	8			8	6	4	6
コンタクト装着力	Contact Insertion Force				2		9	9	9	9
コンタクト単ビン挿入力	Contact Mating Force Per Pin	982 - 3	2	8	8	8 3	8 -	8 3	8	8
コンタクト単ピン引抜力	Contact Unmating Force Per Pin		3			3				5
圧着部引張強度	Crimp Tensile strength	2				-	œ	š	¢	0
耐久性 (繰り返し棒抜)	Durability (Repeated Mating/Unmating)								5	
ハウジングロック強度	Housing Locking Strength			2						į
パネル保持力	Panel Locking strength									
温湿度サイクリング	Humidity-Temperature Cycling									
熱衝撃	Thermal Shock									3
塩水噴霧	Salt Spray		1	j -	j - )	1		3	3	3
コンタクト保持カ	Contact Retention						5			
高温寿命	Temperature Life(Heat Asing)					1				÷
工業ガス(SO <sub>2</sub> )	SO <sub>2</sub>					-				8
ポスト保持力	Post Retention Force		3		3	3		3		3
はんだ付け性	Solderability		S	Sc	S	S				
はんだ耐熱性	Resistance to Soldering Heat	Ĭ								



			試験グループ Test Group							
試験項目	Test or Examination	10	11	12	13	14	15	18	17	8
					- CO	験順 Sequen	100	li .		
製品の確認検査	Confirmation of Product	1,4	1,4	1,4	1.4	1,3	1,3	1,3	1,3	
総合抵抗 (ローレベル)	Termination Resistance (Low Level)	2,5	2,5	2,5	2,5					3
耐電圧	Dielectric withstanding Voltage	7								
絶縁抵抗	Insulation Resistance	6		6						
温度上昇	Temperature Rising									
振動 (高周波)	Vibration (High Frequency)			8					15 14	
衝撃	Physical Shock				)()					ĺ.
コネクタ挿入力	Connector Mating Force									
コネクタ引抜力	Connector Unmating Force									
コンタクト装着力	Contact Insertion Force									
コンタクト挿入力	Contact Mating Force									
コンタクト引抜カ	Contact Unmating Force									
圧着部引張強度	Crimp Tensile strength			8						
耐久性 (繰り返し挿抜)	Durability (Repeated Mating/Unmating)									
ハウジングロック強度	Housing Locking Strength			2						
パネル保持力	Panel Locking strength			8					2	
温湿度サイクリング	Humidity-Temperature Cycling	3		(e						
熱衝撃	Thermal Shock	15.73								
塩水噴霧	Salt Spray		3		ũ ũ	Ĩ				Ü
コンタクト保持カ	Contact Retention Force			i i						
高温寿命	TemperatureLife(Heat Asing)			3						
工業ガス(SO <sub>2</sub> )	SO <sub>2</sub>				3					
ポスト保持力	Post Retention Force				Ĵ Ŭ	2				Ű
はんだ付け性	Solderability	1		1	î î	1	2		27	
はんだ耐熱性	Resistance to Soldering Heat	183 8		3	8 3	- 8	3	2		

### Notes:

- a. Numbers indicate the sequence in which the tests are performed.
- b. Test group as below table 2 shown

Testing part	Testing part description	Test group	Plating
1-2271888-4	HDR ASSY (H-TYPE) 2.0mm Pitch 28POS.Tin plating	5,8,9,10,11,12,13	1.0um Tin

Table 2 test group



## 3. Test result

Group	Sequence	Test items	Requirements	Test data	Result
6	1	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept
Group	2	Temperature rising	Temperature rising: 30°C Max.	8.94~13.53°C	Accept
3	3	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept

Group	Sequence	Test items	Requirements	Test data	Result	
	1	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept	
	2	Termination Resistance (Low Level)	10mΩ Max. (Initial)	2.51~4.17mΩ	Accept	
	3	Connector Mating Force	Connector Mating Force 5.88N Max. Per Contact			
Group 8	4	Connector Unmating Force	1.0.58N Min. Per Contact (1 <sup>ST</sup> Cycle) 2.0.29 N Min. (30 <sup>th</sup> Cycle)	1.2.07~2.98N 2.1.61~2.29N	Accept	
	5	Durability (Repeated Mate / Unmating)	1.No physical damage 2.Temination Resistance	1.No physical damage 2. Refer to sequence 6	Accept	
	6	Termination Resistance (Low Level)	20mΩ Max. (Final)	2.98~5.86mΩ	Accept	
	7	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept	

Group	Sequence	Test items	Requirements	Test data	Result
	1	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept
	2	Termination Resistance (Low Level)	10mΩ Max. (Initial)	1.58~3.74mΩ	Accept
Group 9	3	Thermal Shock	1.No physical damage 2.Temination Resistance	<ul><li>1.No physical damage</li><li>2. Refer to sequence 4</li></ul>	Accept
	4	Termination Resistance (Low Level)	20mΩ Max. (Final)	2.42~4.15mΩ	Accept
	5	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept



Group	Sequence	Test items	Requirements	Test data	Result
	1	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept
	2	Termination Resistance (Low Level)	10mΩ Max. (Initial)	2.28~3.88mΩ	Accept
	3	Insulation Resistance	1000MΩ Min.	>9999 MΩ	Accept
Crown	4	Dielectric withstanding Voltage	Neither creeping discharge nor flashover shall occur. Current leakage: 0.5 mA Max.	1.No breakdown 2. 0.025~0.031mA	Accept
Group 10	5	Humidity-Temperature Cycling	Dielectric Strength; Insulation resistance; Termination resistance (Low Level)	Refer to sequence 8 Refer to sequence 7 Refer to sequence 6	Accept
	6	Termination Resistance (Low Level)	20mΩ Max. (Initial)	2.25~3.90mΩ	Accept
	7	Insulation Resistance	100MΩ Min.	>9999 MΩ	Accept
	8	Dielectric withstanding Voltage	Neither creeping discharge nor flashover shall occur. Current leakage: 0.5 mA Max.	1.No breakdown 2. 0.027~0.033mA	Accept

Group	Sequence	Test items	Requirements	Test data	Result
	1	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept
	2	Termination Resistance (Low Level)	10mΩ Max. (Initial)	2.11~3.54mΩ	Accept
Group 11	3	Salt Spray	1.No corrosion influence     performance     2.Termination Resistance	1.Slight corrosion external, no impact on performance 2.Refer to sequence 4	Accept
	4	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept
	5	Termination Resistance (Low Level)	20mΩ Max. (Final)	1.78~8.17mΩ	Accept



Group	Sequence	Test items	Requirements	Test data	Result
	1	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept
	2	Termination Resistance (Low Level)	10mΩ Max. (Initial)	2.11~3.74mΩ	Accept
Group	3	Temperature life	Termination Resistance	Refer to sequence 5	Accept
12	4	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept
	5	Termination Resistance (Low Level)	20mΩ Max. (Final)	2.12~4.19mΩ	Accept

Group	Sequence	Test items	Requirements	Test data	Result
	1	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept
	2	Termination Resistance (Low Level)	10mΩ Max. (Initial)	3.07~3.87mΩ	Accept
Group 13	3	Industrial Gas (SO2)	<ul><li>1.No physical damage impact performance</li><li>2.Termination Resistance</li></ul>	1.Refer to sequence 4 2.Refer to sequence 5	Accept
	4	Examination of Product	Meets requirements of product drawing and Specification 114-5377	No physical damage	Accept
	5	Termination Resistance (Low Level)	20mΩ Max. (Final)	2.08~4.35mΩ	Accept

